

\*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

# **Thermal Characteristics**

TJ

Symbol	Parameter	Value	Units		
PD	Power Dissipation	1.8	W		
R <sub>eJA</sub>	Thermal Resistance, Junction to Ambient*	80	°C/W		
$R_{ ext{ ext{ ext{ ext{ ext{ ext{ ext{ ext$	Thermal Resistance, Junction to Lead*	26	°C/W		

-65 to +175

\*Device mounted on PCB with 0.2 x 0.2" (5.0 x 5.0 mm) copper pad areas.

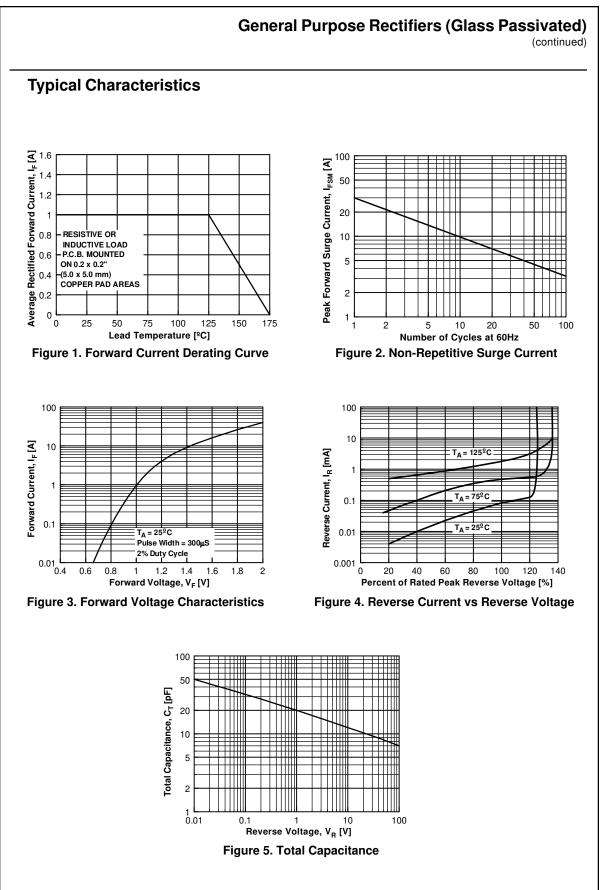
**Operating Junction Temperature** 

## Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		Device							Units
		1	1A	1B	1D	1G	1J	1K	1M	
V <sub>F</sub>	Forward Voltage @ 1.0 A				1.0			1	.2	V
t <sub>rr</sub>	Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$		2.0					μs		
I <sub>R</sub>		= 25°C = 125°C	5.0 50					μΑ μΑ		
C <sub>T</sub>	Total Capacitance $V_{B} = 4.0 V, f = 1.0 MHz$		15					pF		

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°C



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GF1A-GF1M, Rev. G

# GF1A-GF1M

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